

FIG. 1A

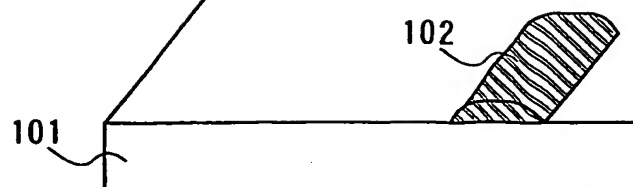


FIG. 1B

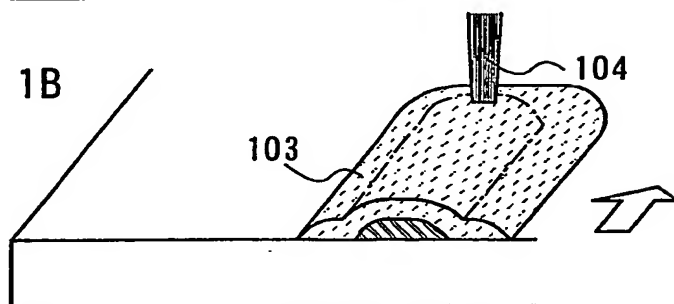


FIG. 1C

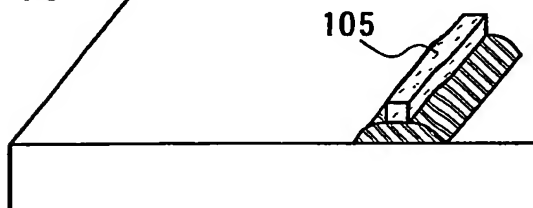


FIG. 1D

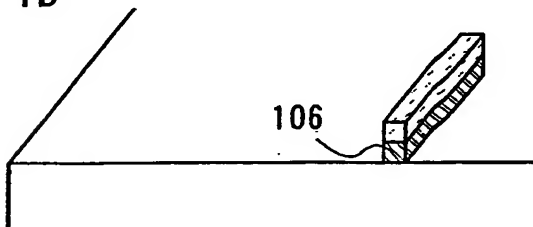
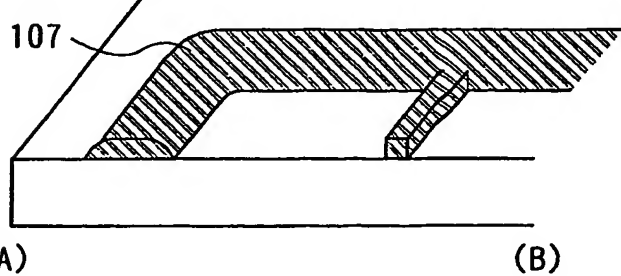


FIG. 1E



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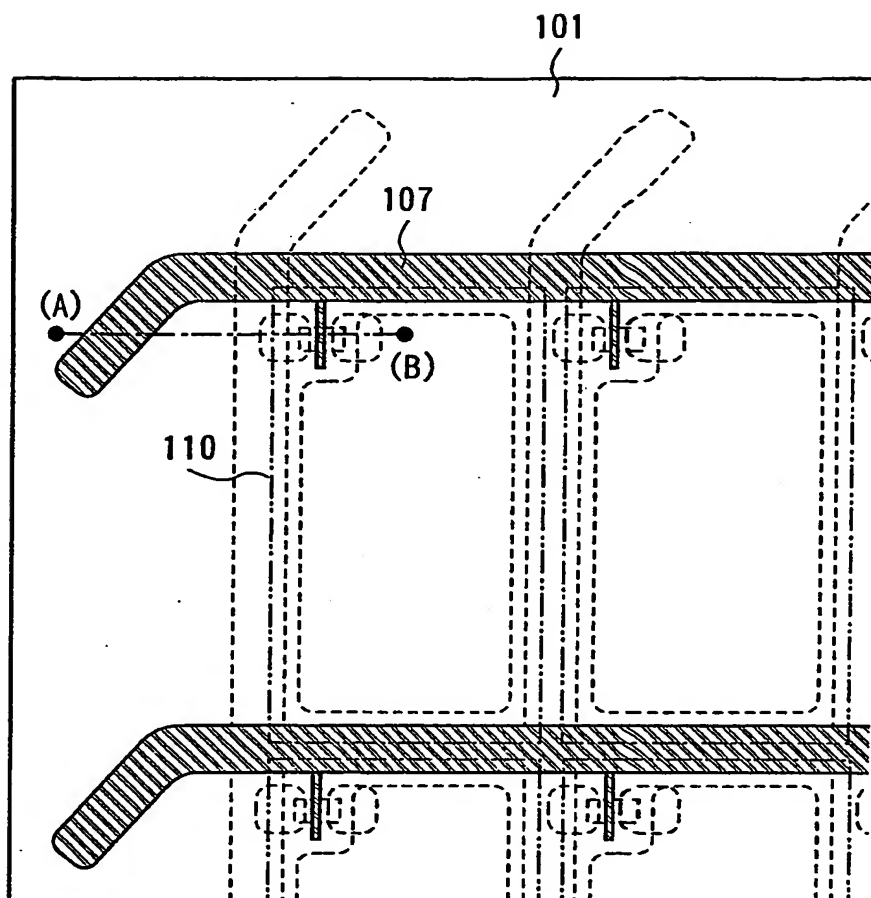


FIG. 2

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FIG. 3A

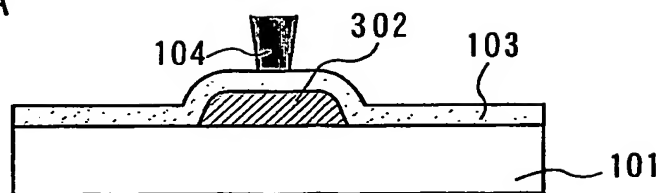


FIG. 3B

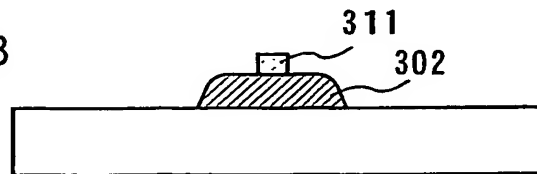


FIG. 3C

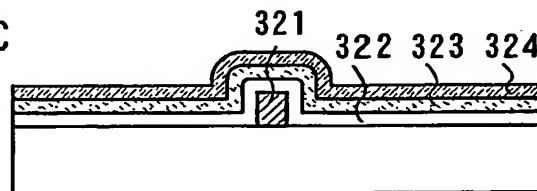


FIG. 3D

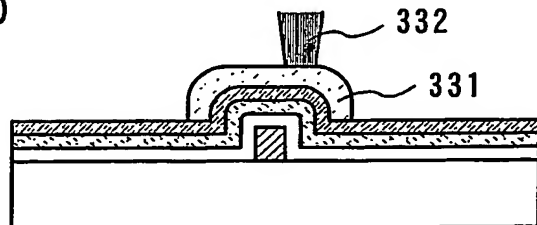


FIG. 3E

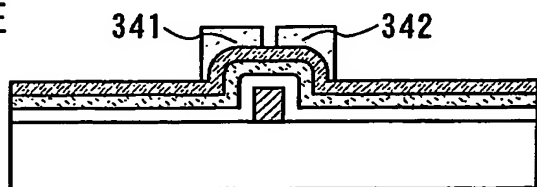
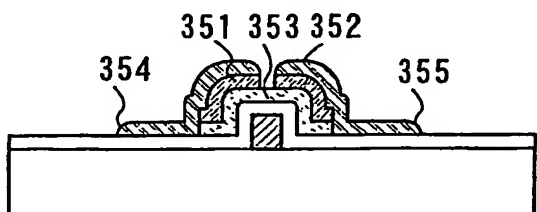


FIG. 3F



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FIG. 4A

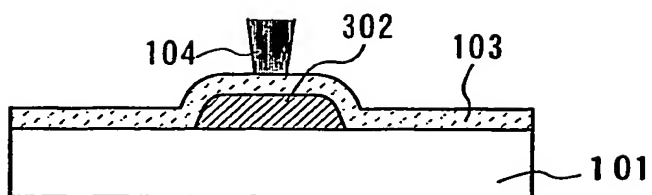


FIG. 4B

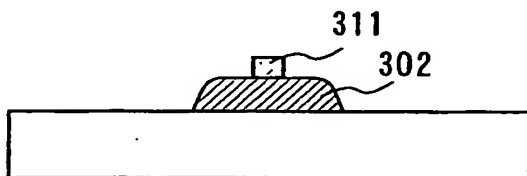


FIG. 4C

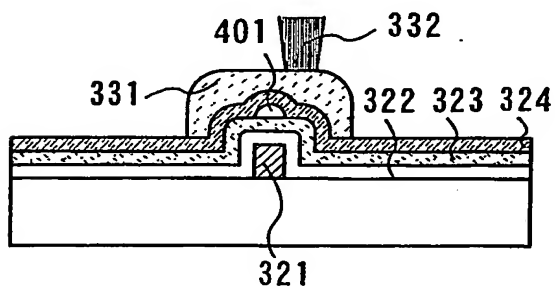


FIG. 4D

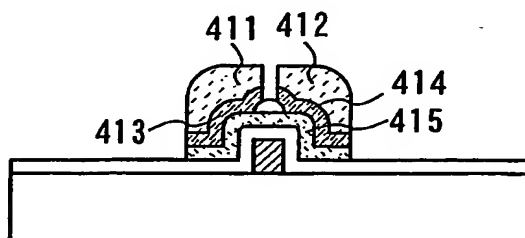
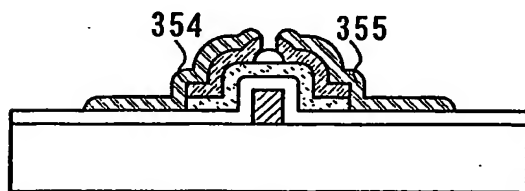


FIG. 4E



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FIG. 5A

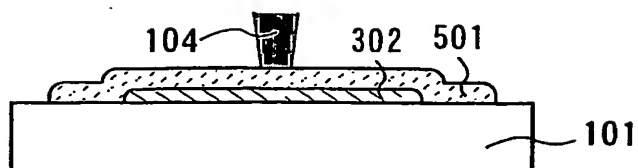


FIG. 5B

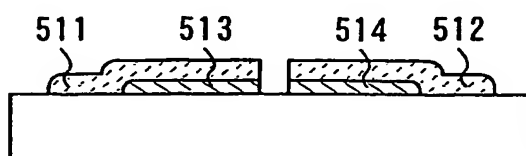


FIG. 5C

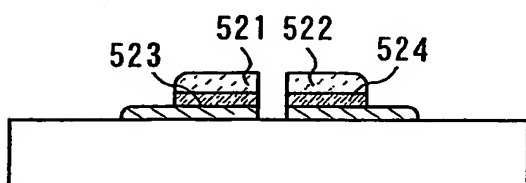


FIG. 5D

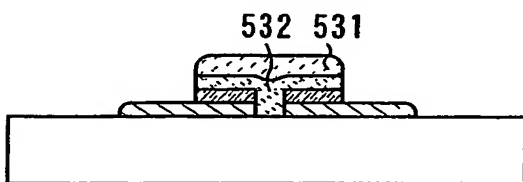


FIG. 5E

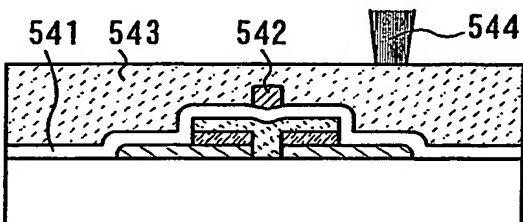


FIG. 5F

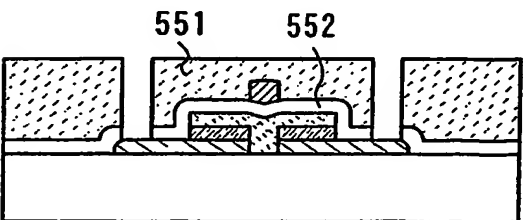


FIG. 5G

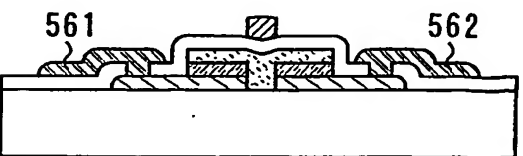


FIG. 6A

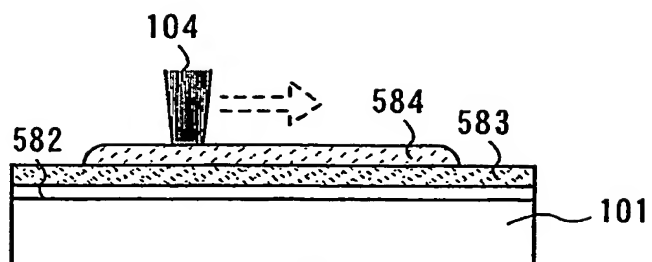


FIG. 6B

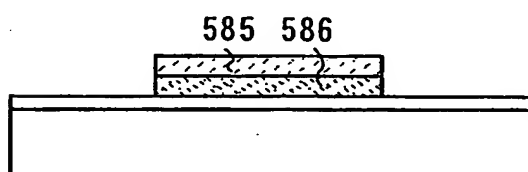


FIG. 6C

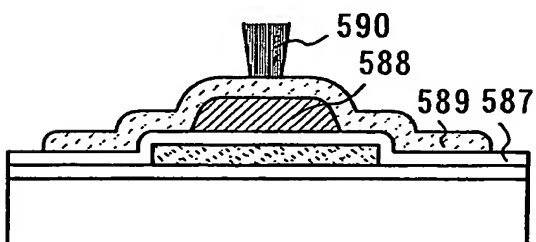


FIG. 6D

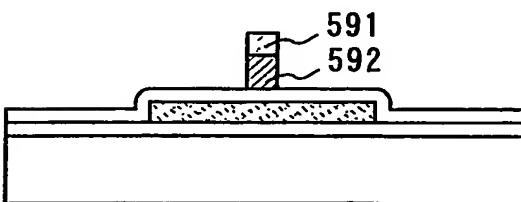
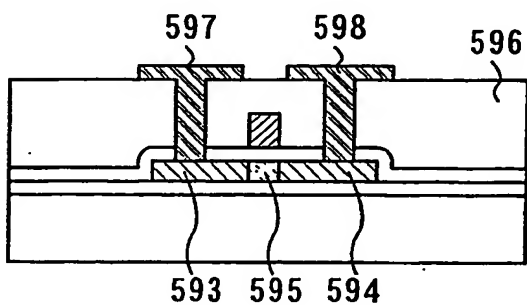
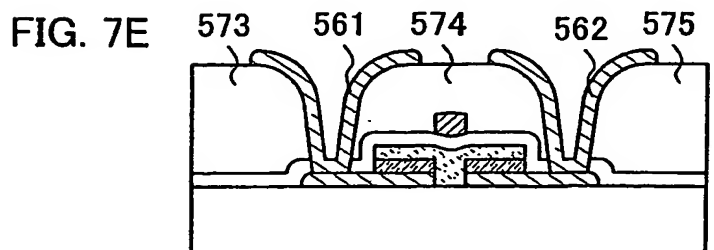
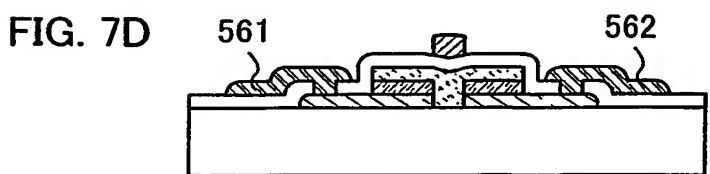
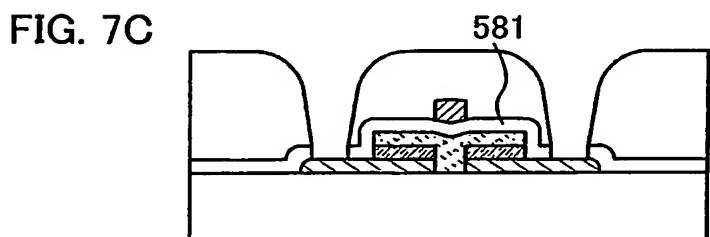
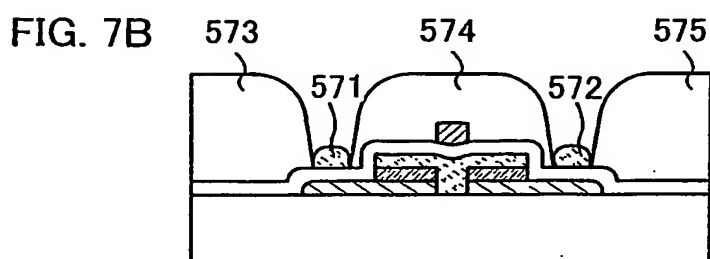
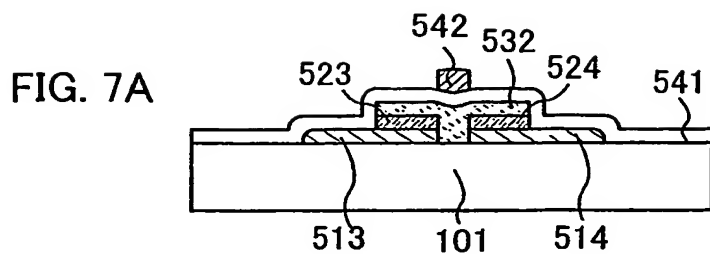


FIG. 6E





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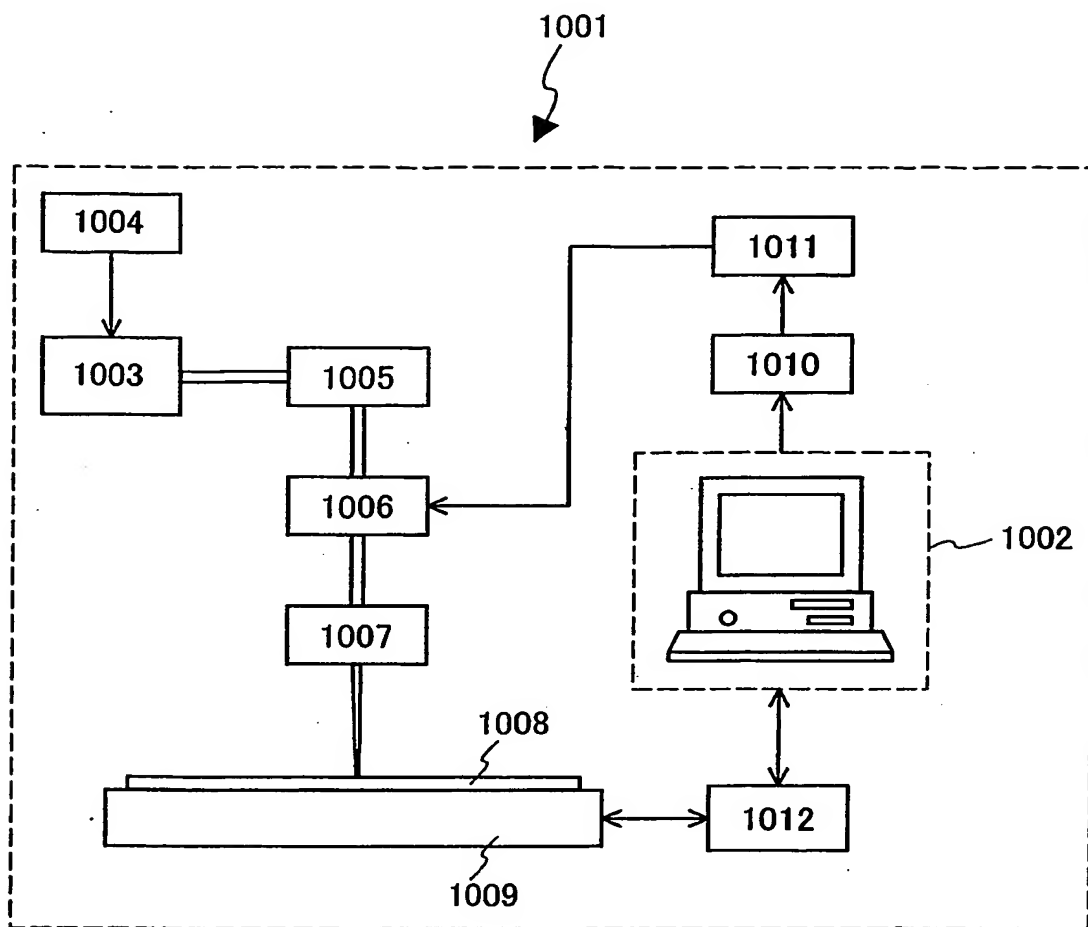


FIG. 8

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FIG. 9A

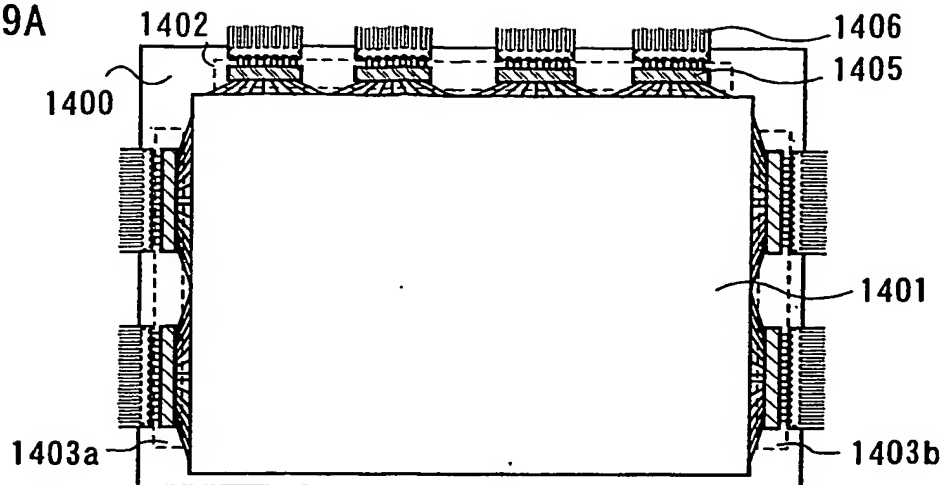


FIG. 9B

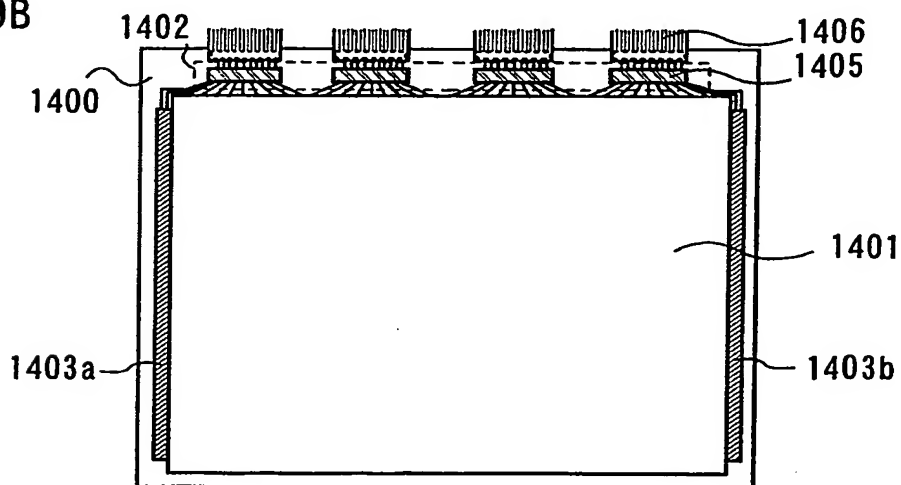
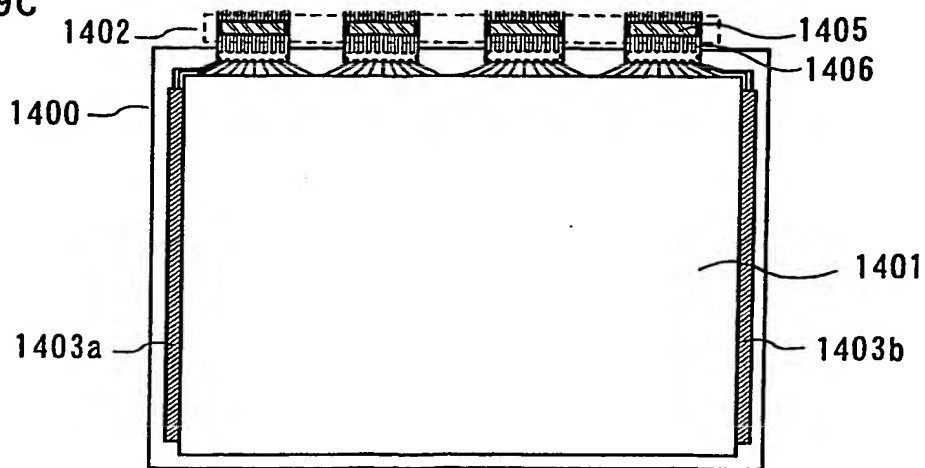


FIG. 9C



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FIG. 10A

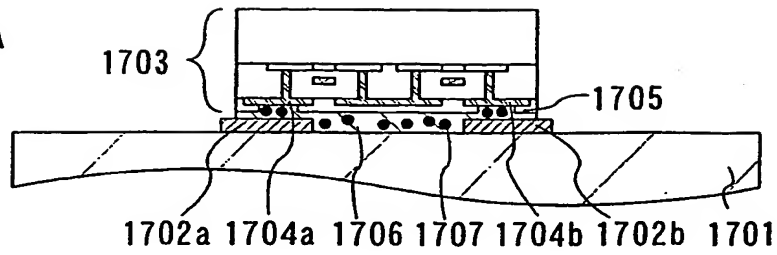


FIG. 10B

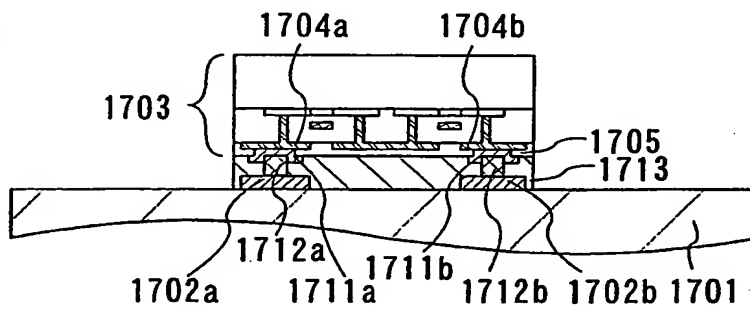


FIG. 10C

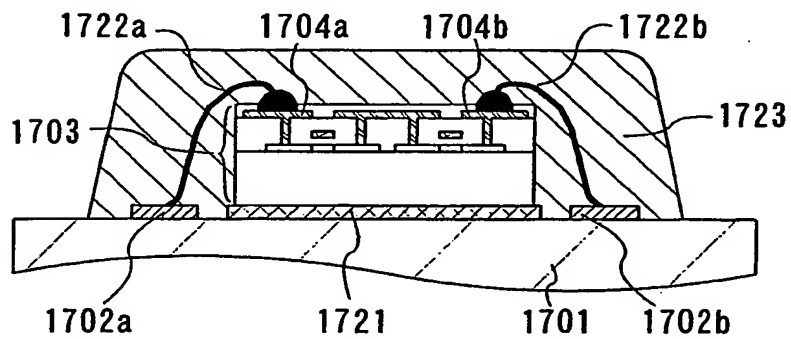
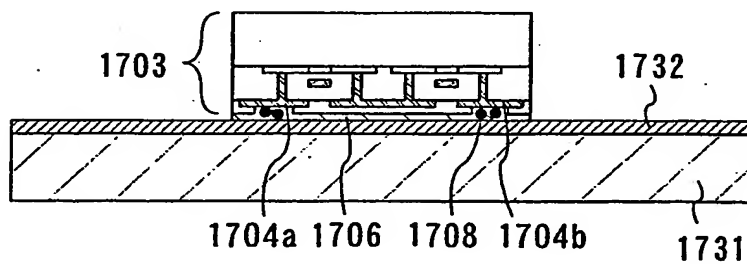


FIG. 10D



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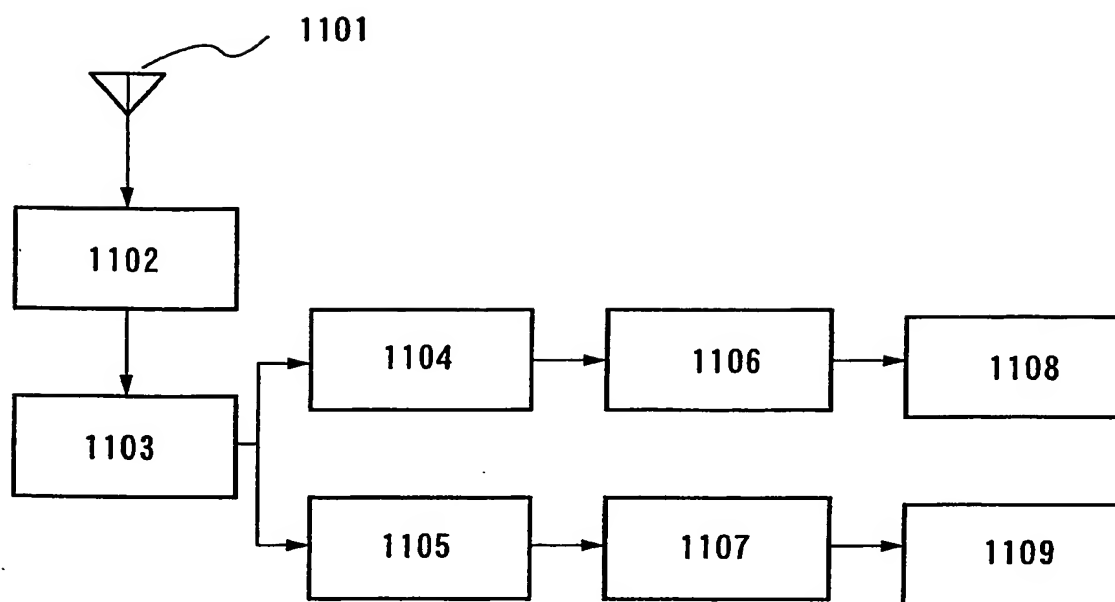


FIG. 11

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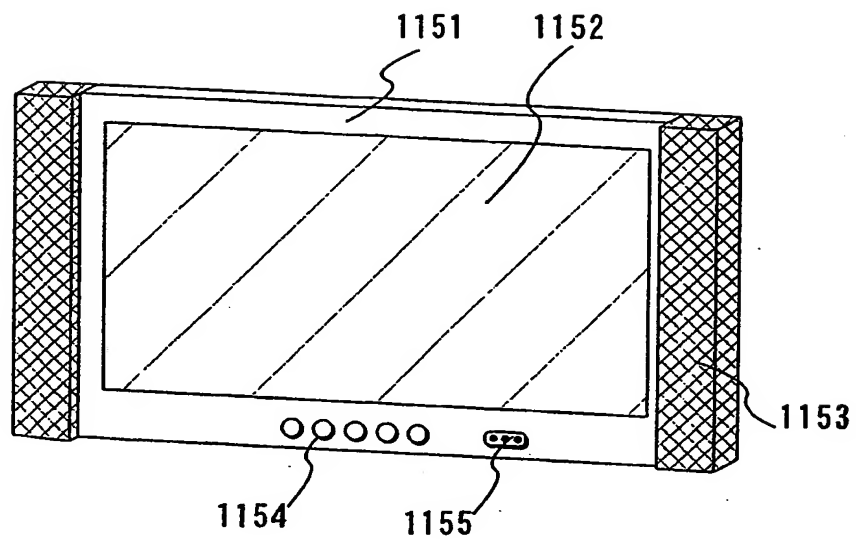


FIG. 12

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FIG. 13A

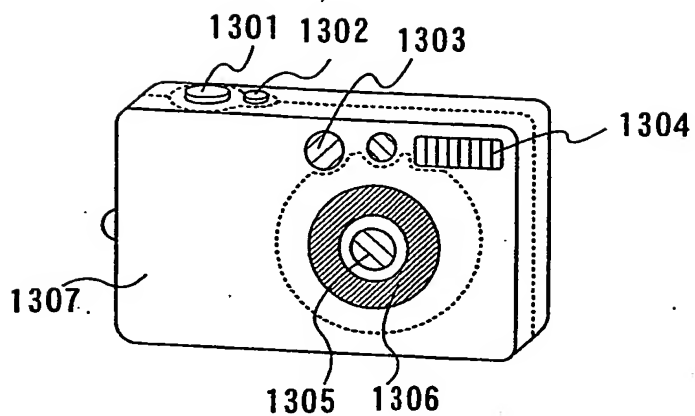
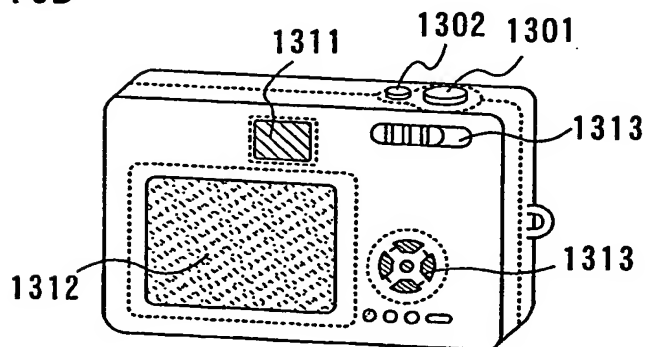


Fig. 13B



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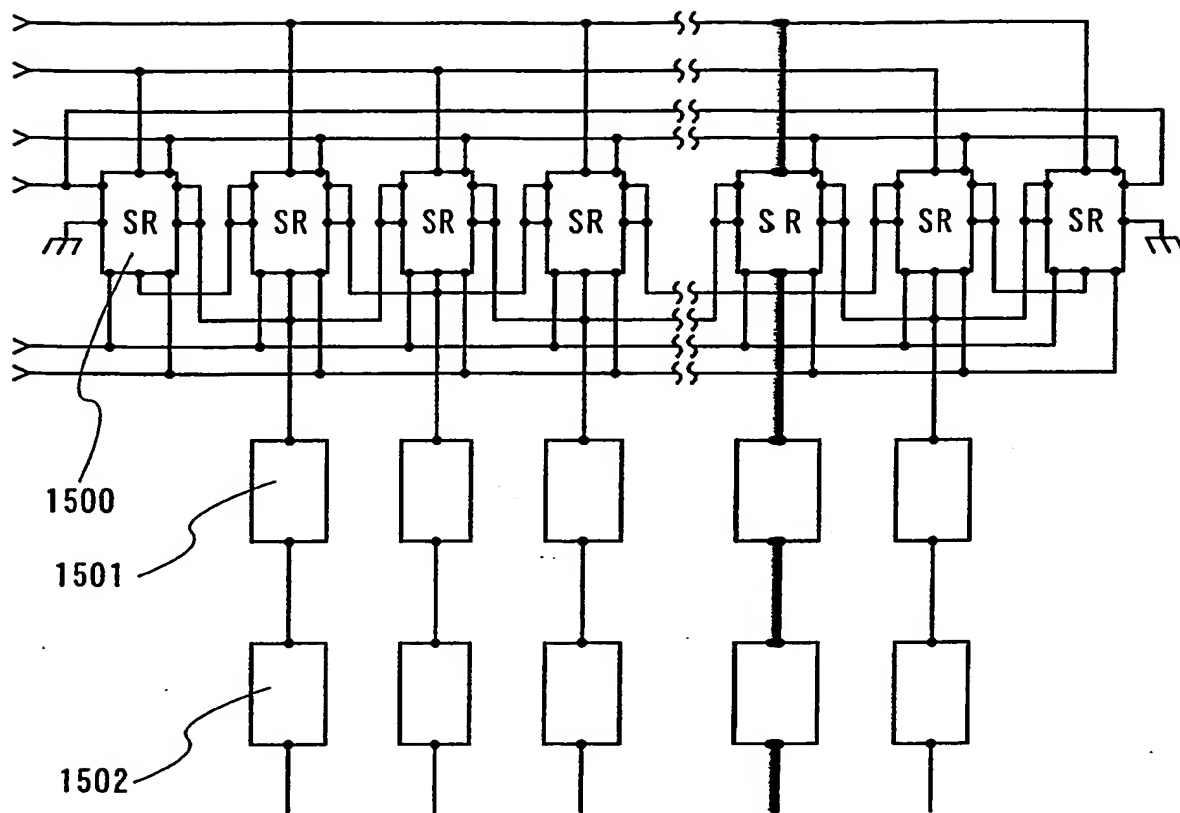


FIG. 14

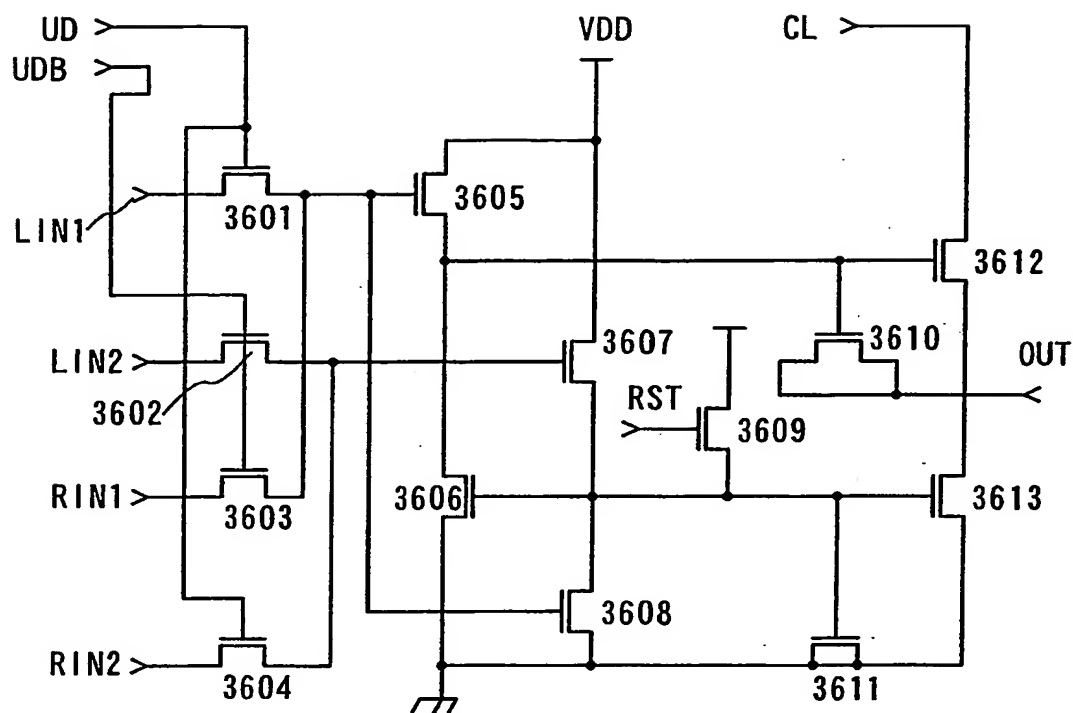


FIG. 15

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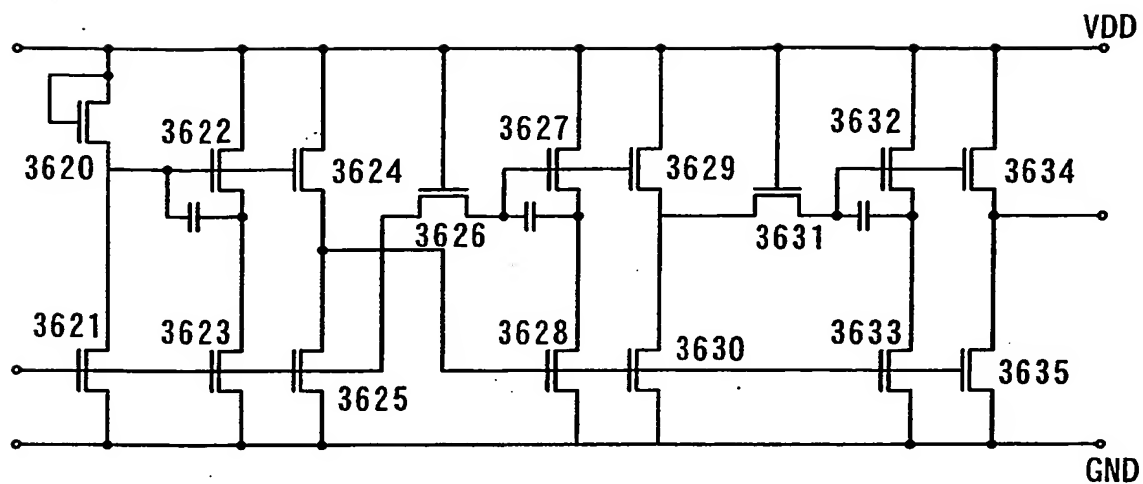


FIG. 16

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FIG. 17A

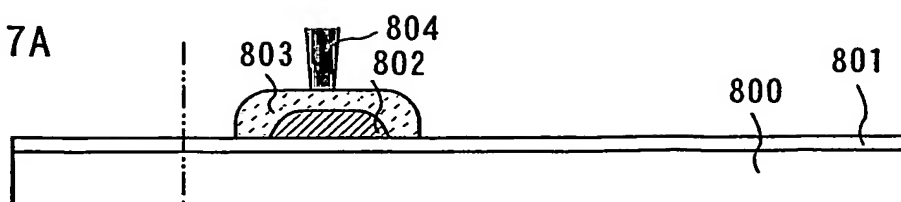


FIG. 17B

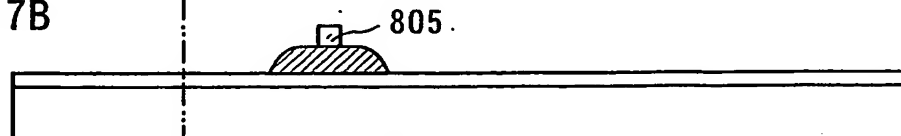


FIG. 17C

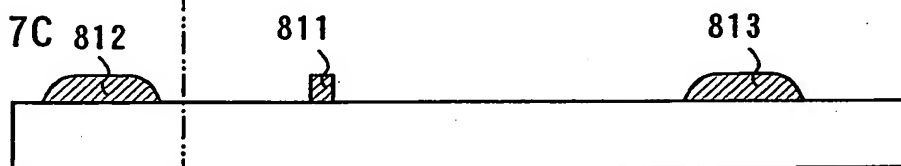


FIG. 17D

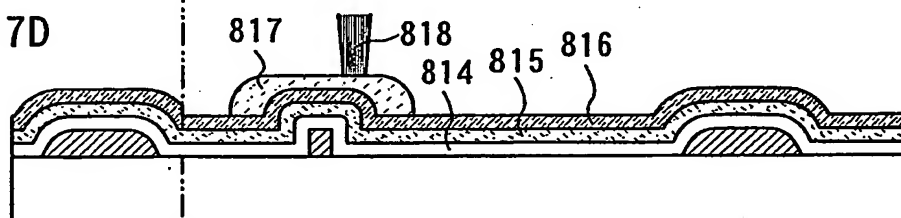


FIG. 17E

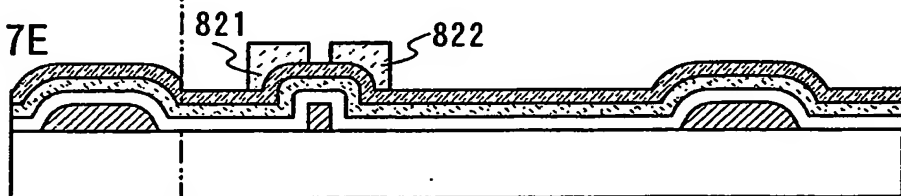


FIG. 17F

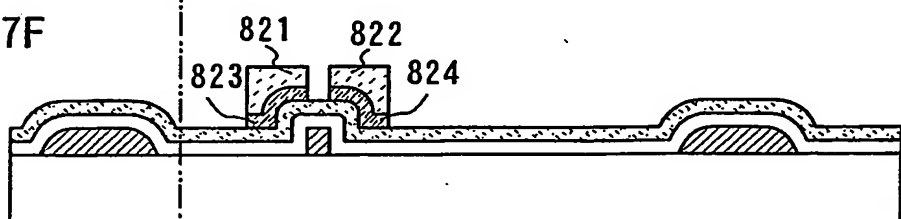
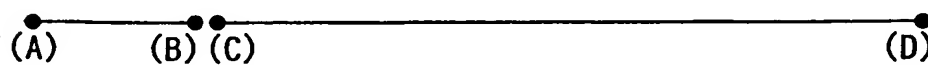
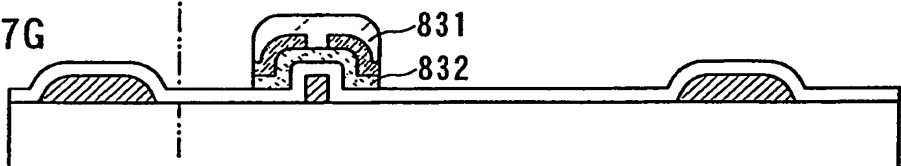


FIG. 17G



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FIG. 18A

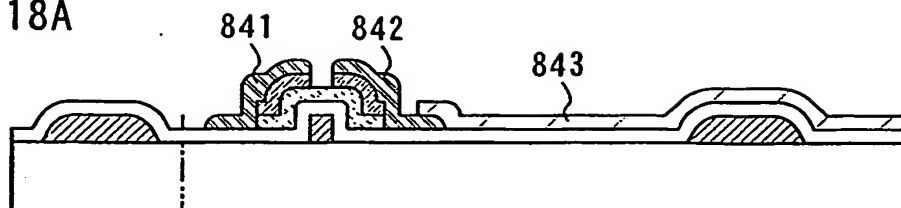


FIG. 18B

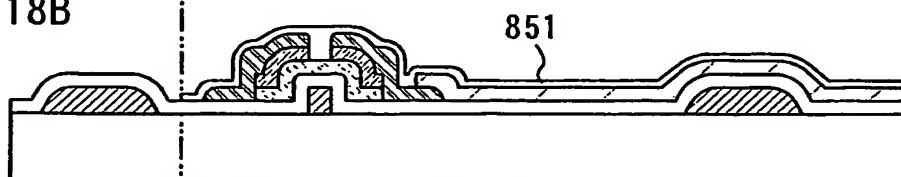


FIG. 18C

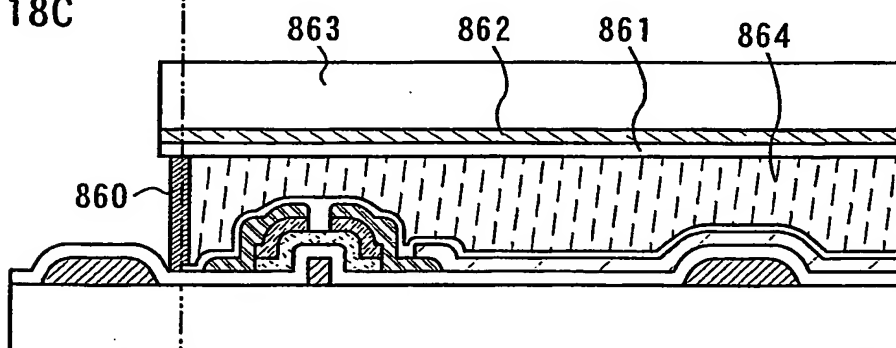
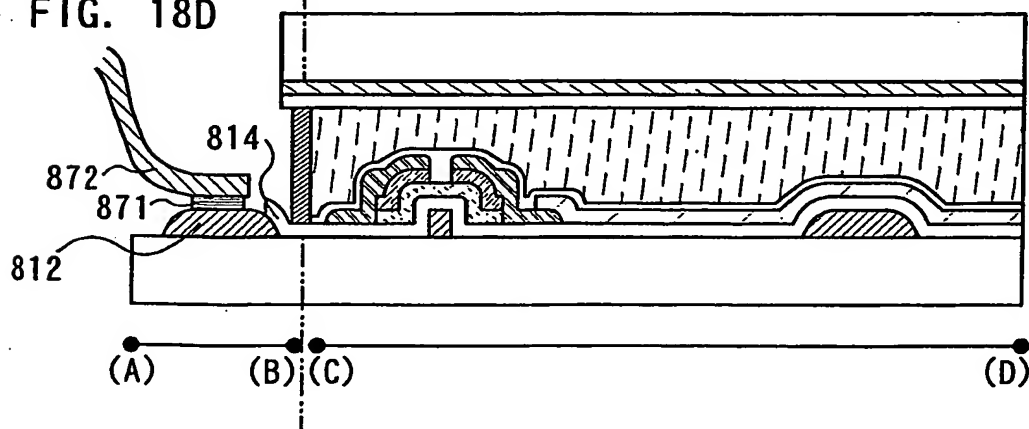


FIG. 18D



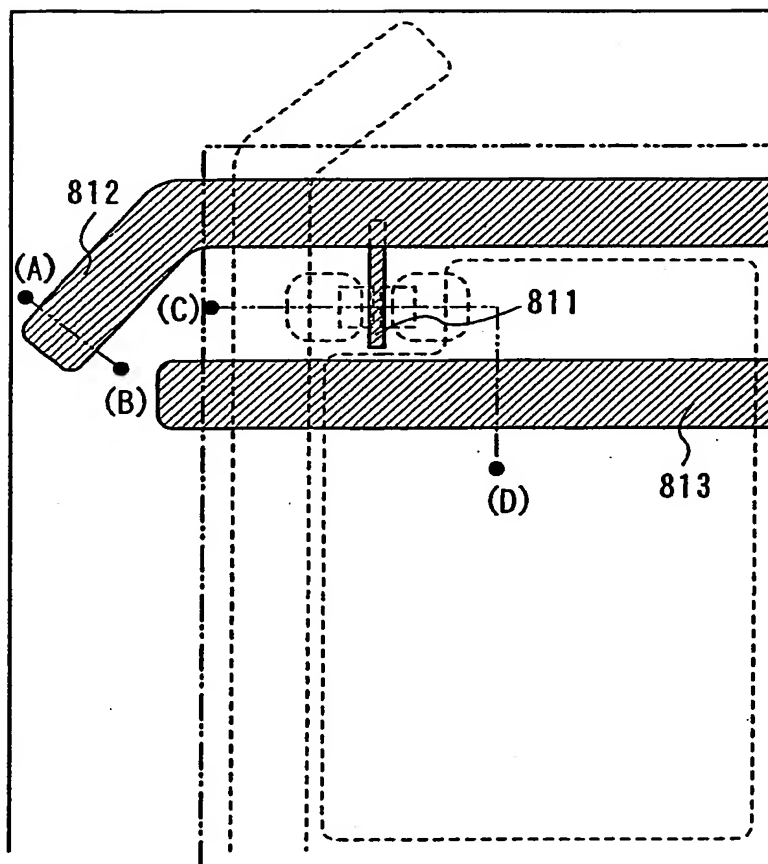


FIG. 19

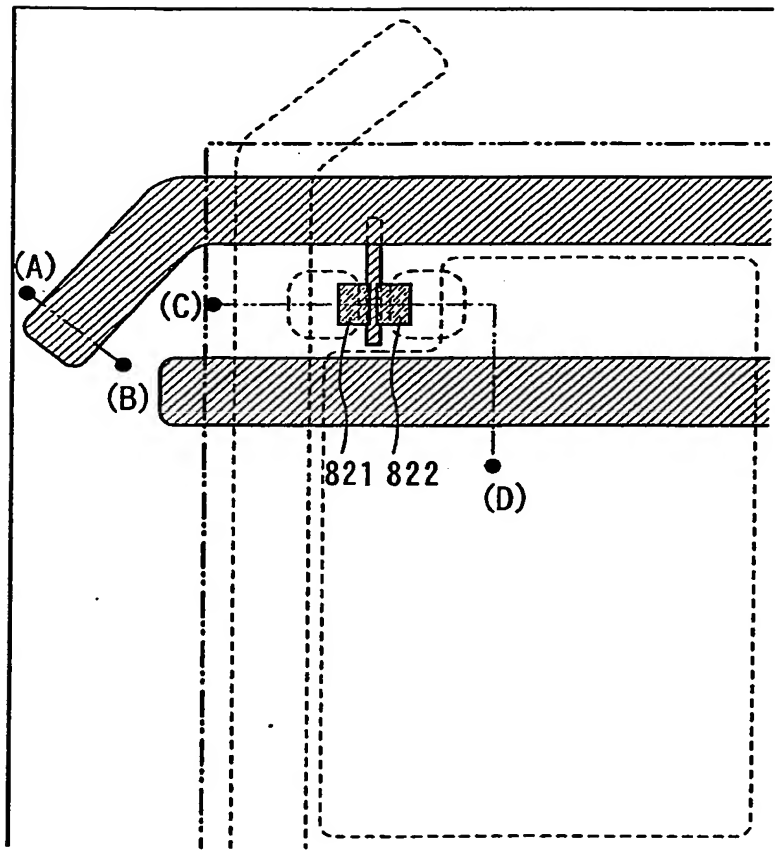


FIG. 20

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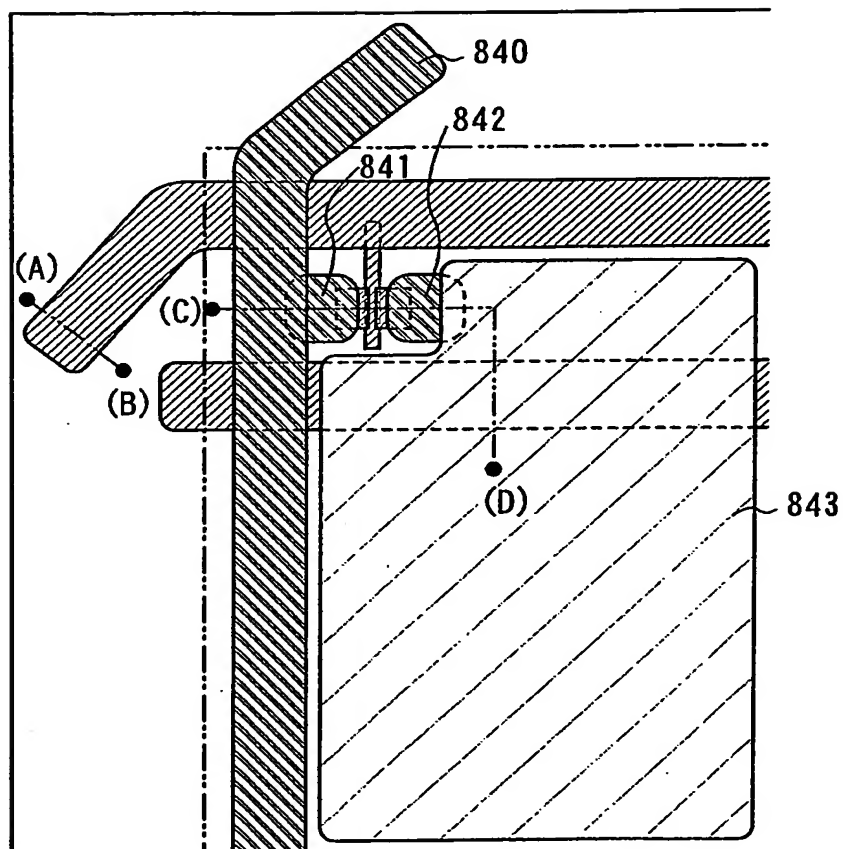


FIG. 21

FIG. 22A

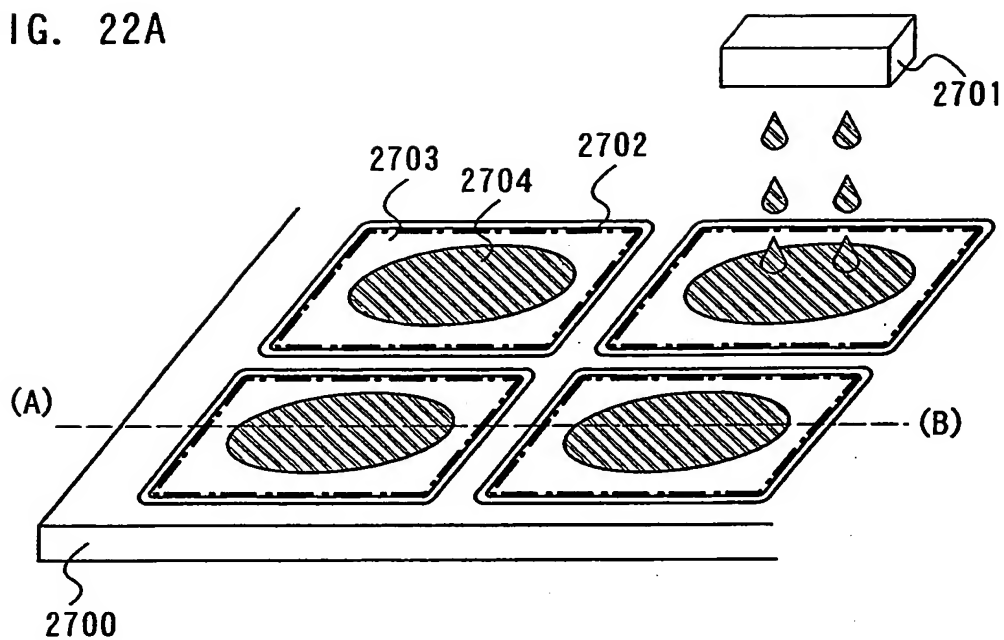
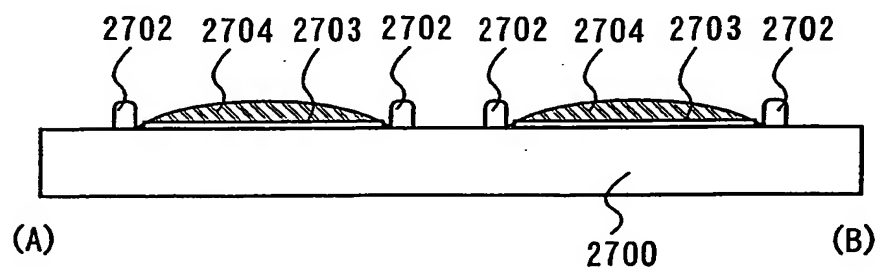


FIG. 22B



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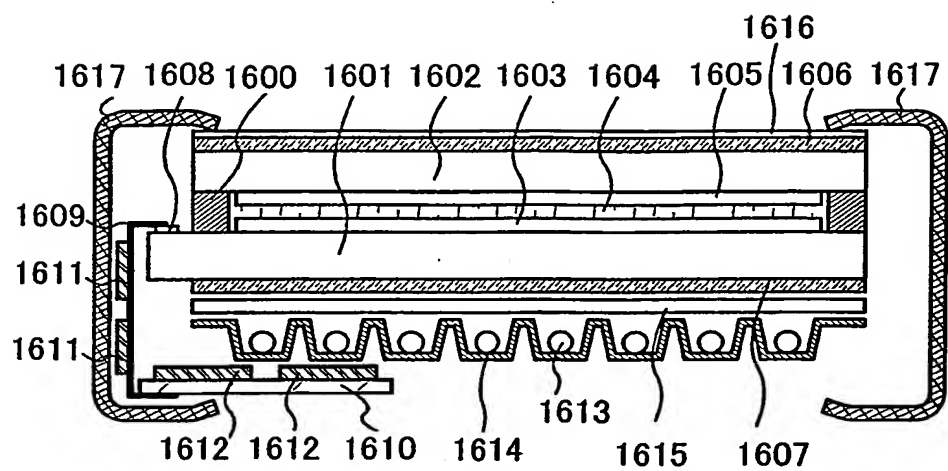


FIG. 23

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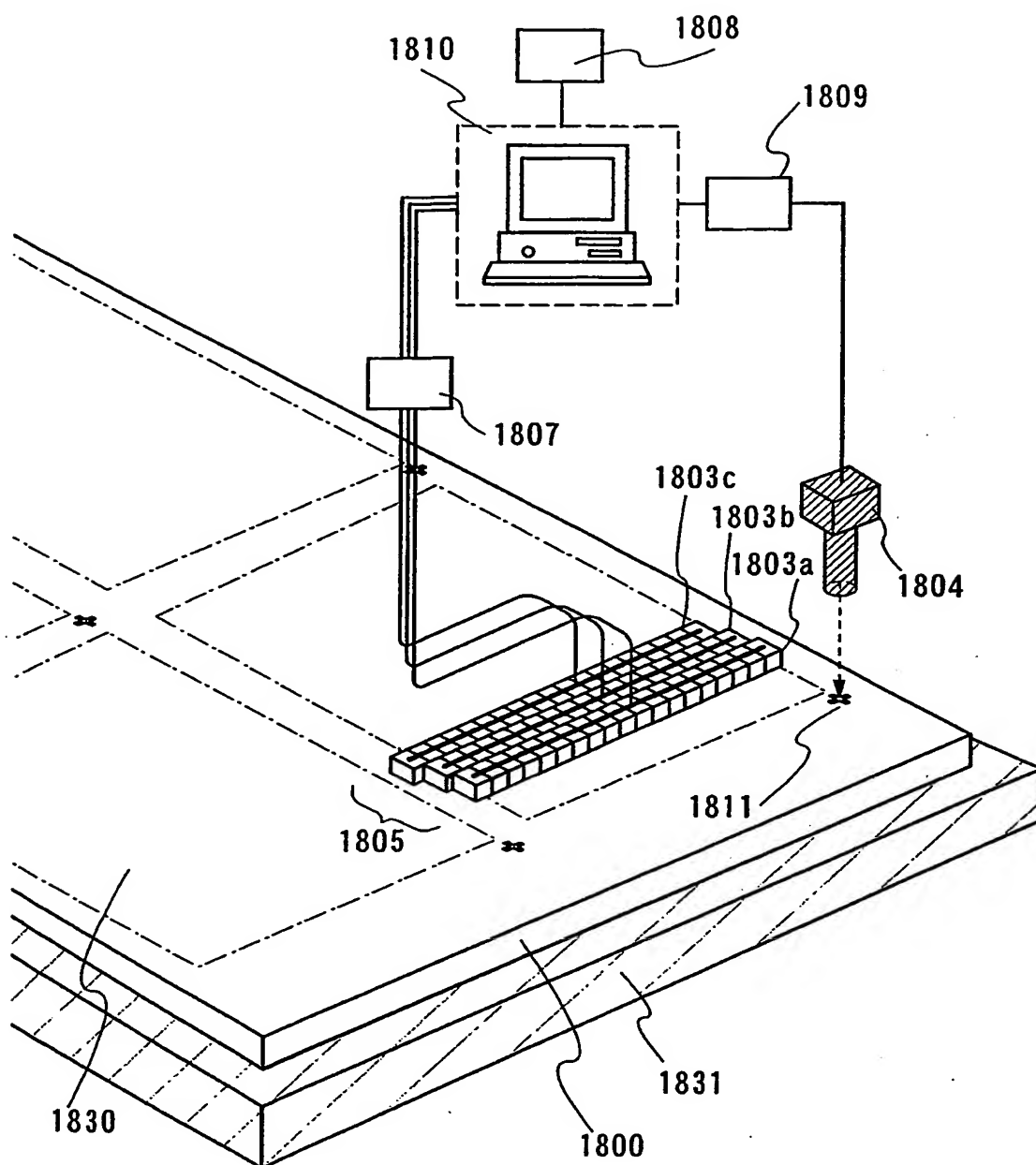


FIG. 24

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FIG. 25A

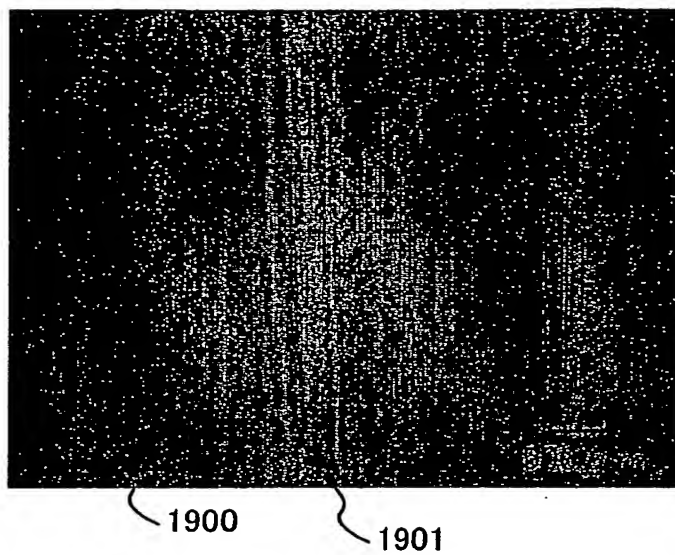
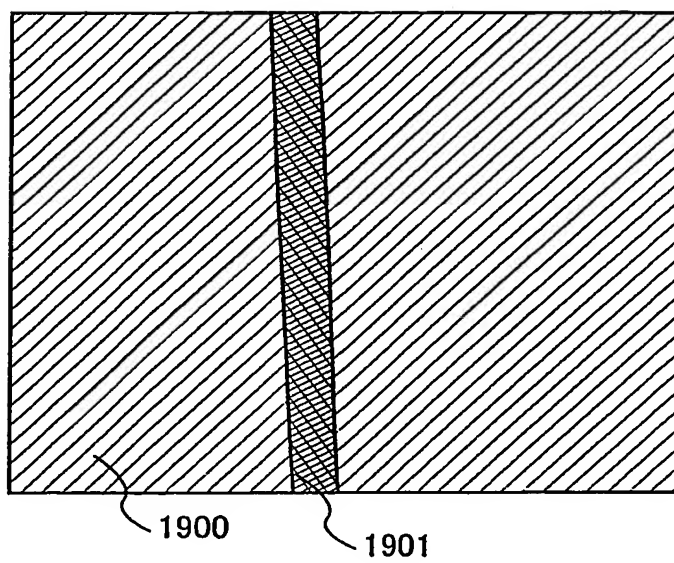


FIG. 25B



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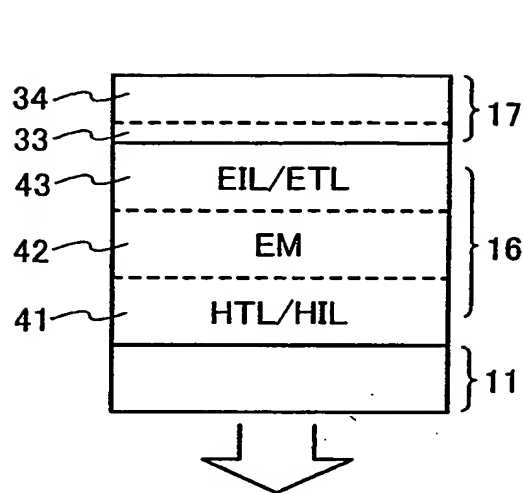


FIG. 26A

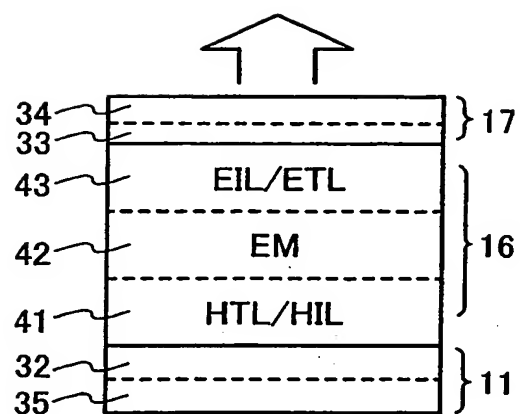


FIG. 26B

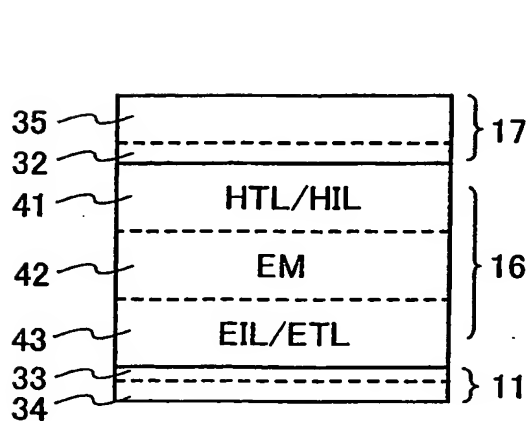


FIG. 26C

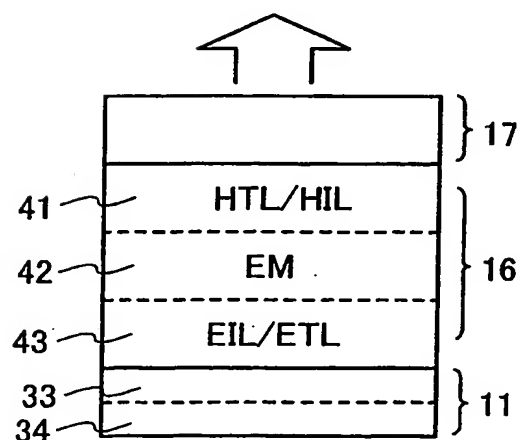


FIG. 26D

FIG. 27A

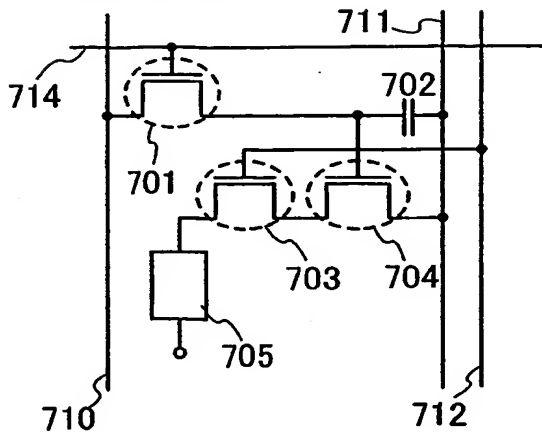


FIG. 27B

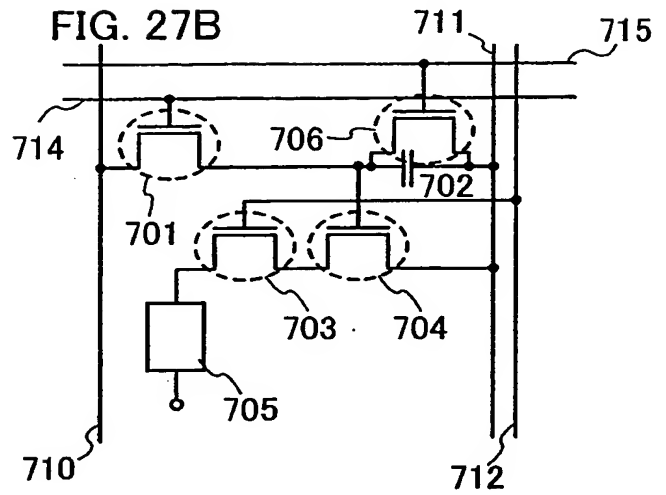


FIG. 27C

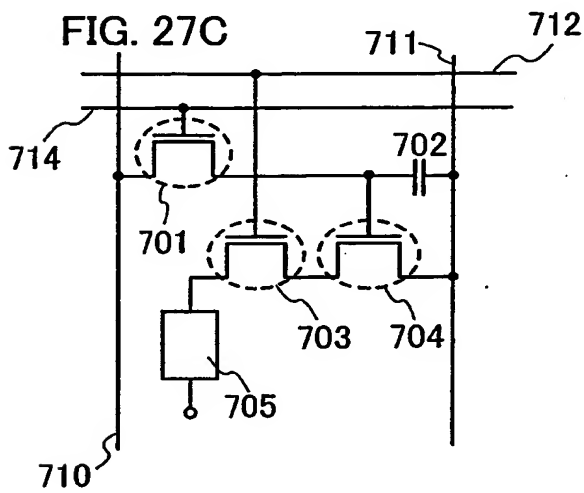


FIG. 27D

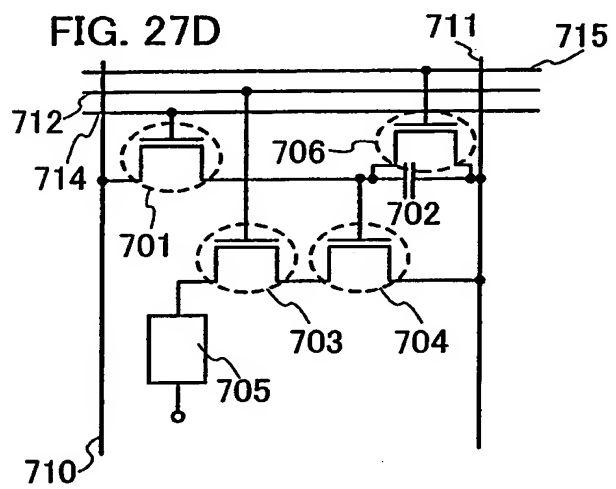


FIG. 27E

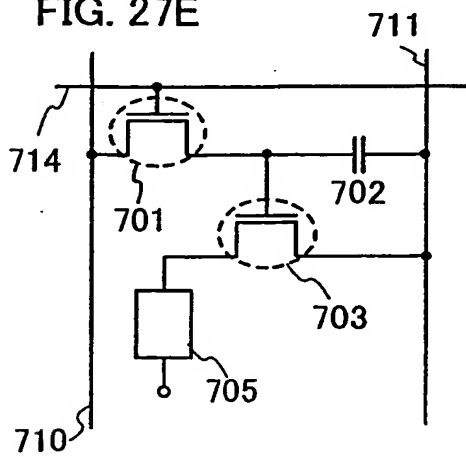
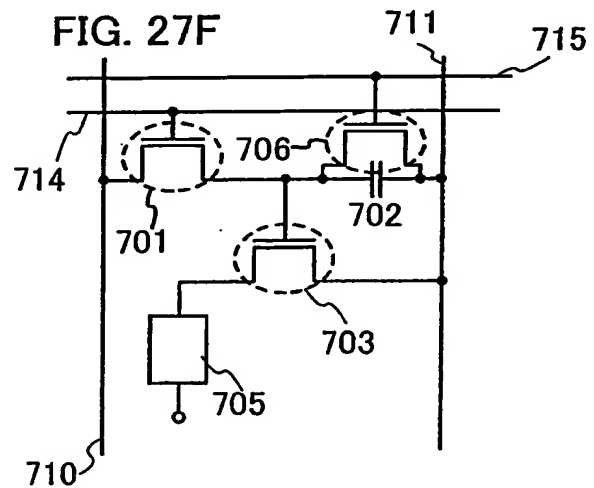


FIG. 27F



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FIG. 28A

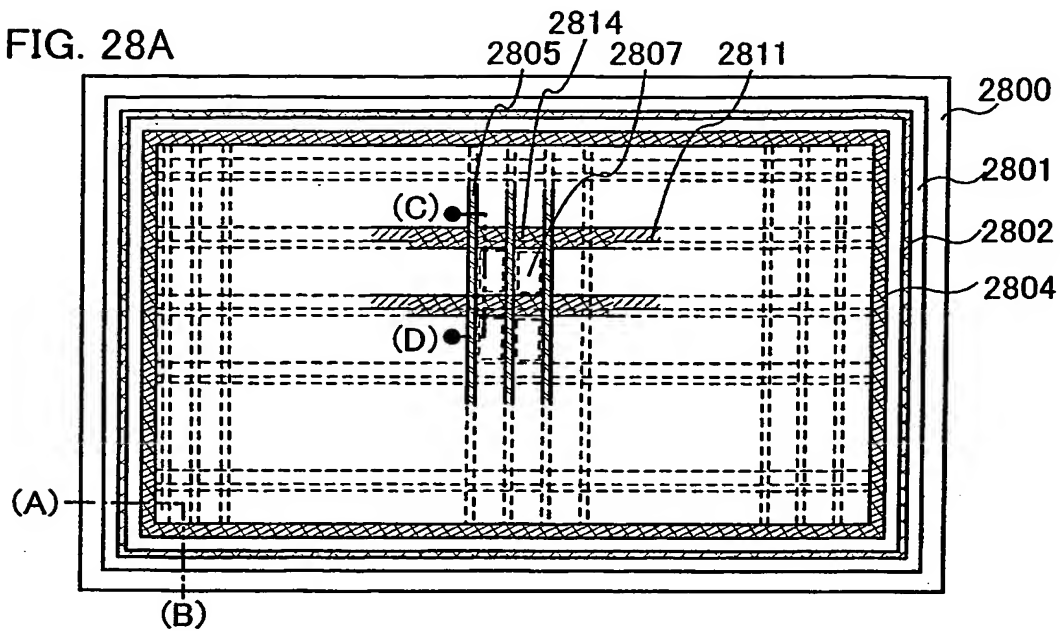


FIG. 28B

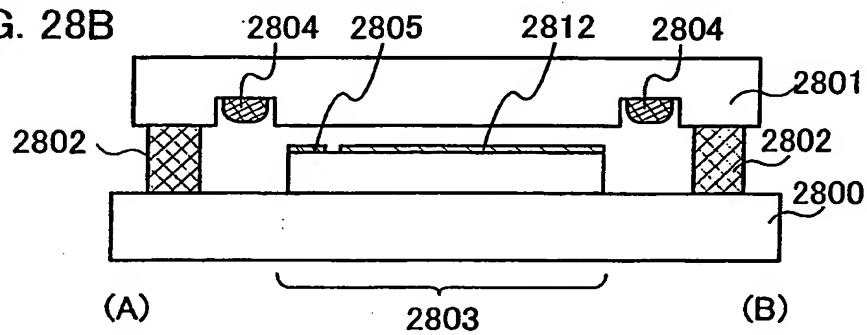
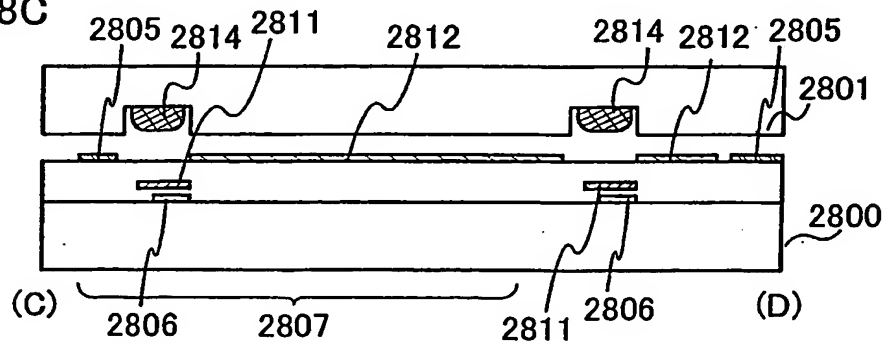


FIG. 28C



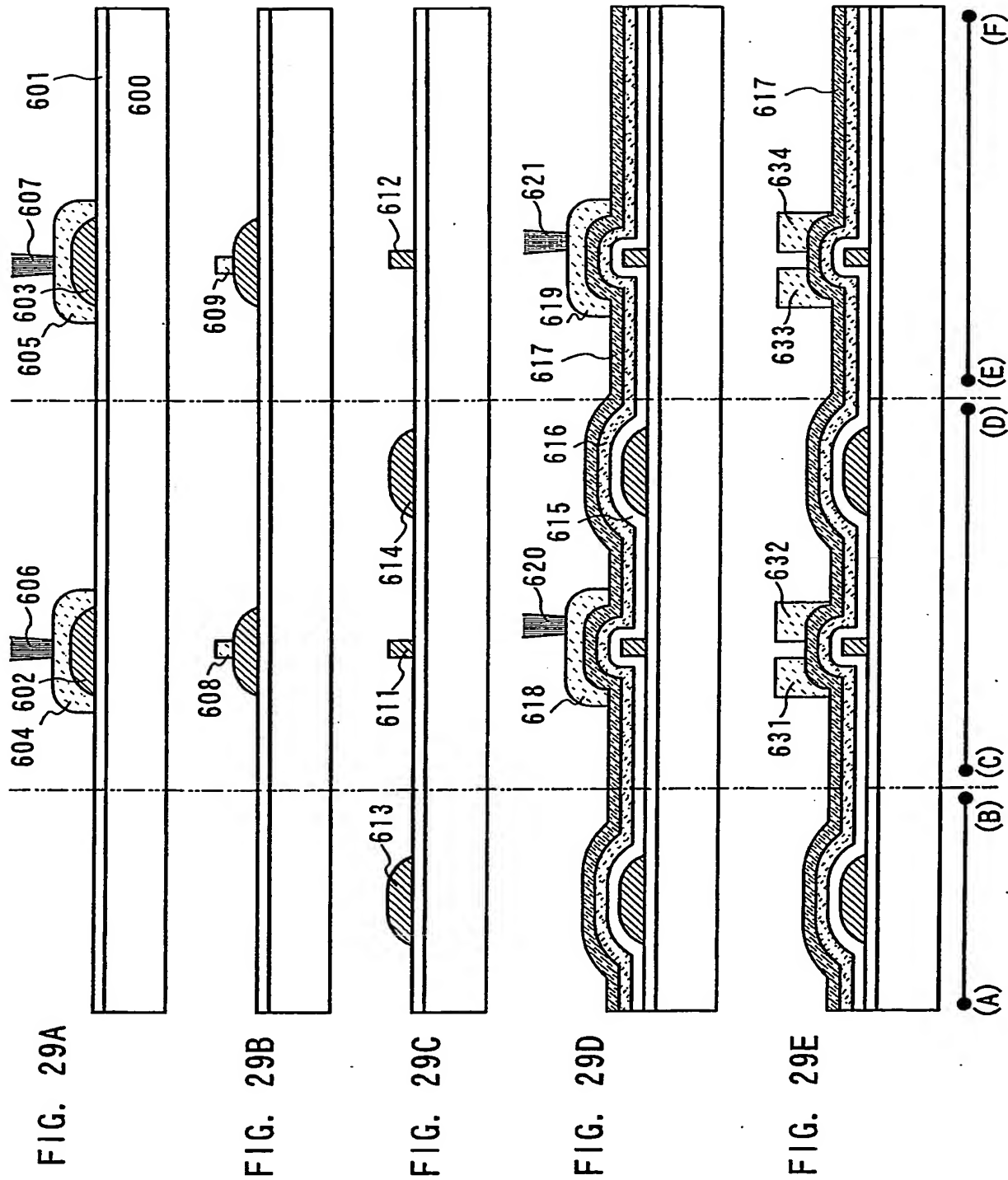


FIG. 30A

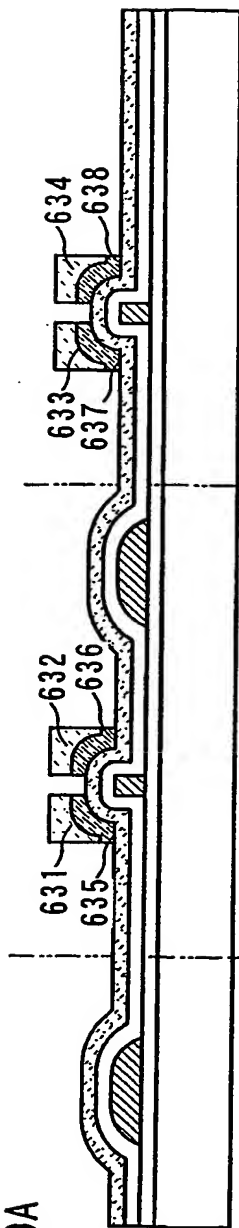


FIG. 30B

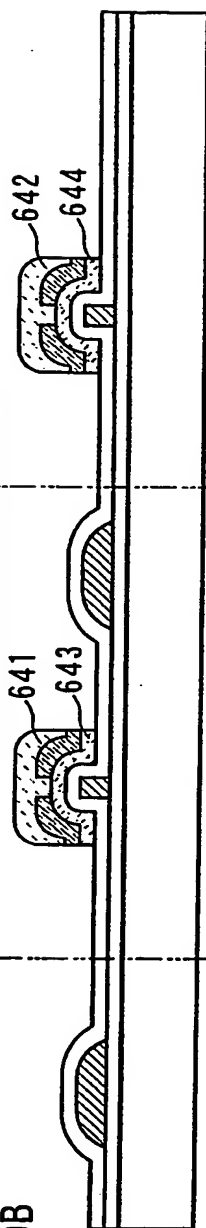


FIG. 30C

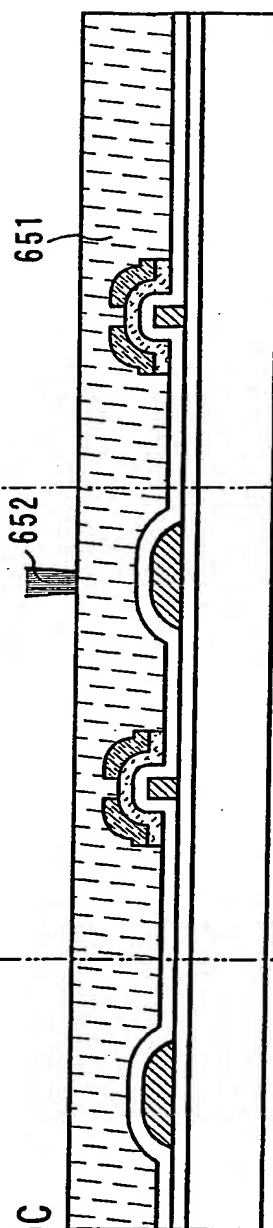


FIG. 30D

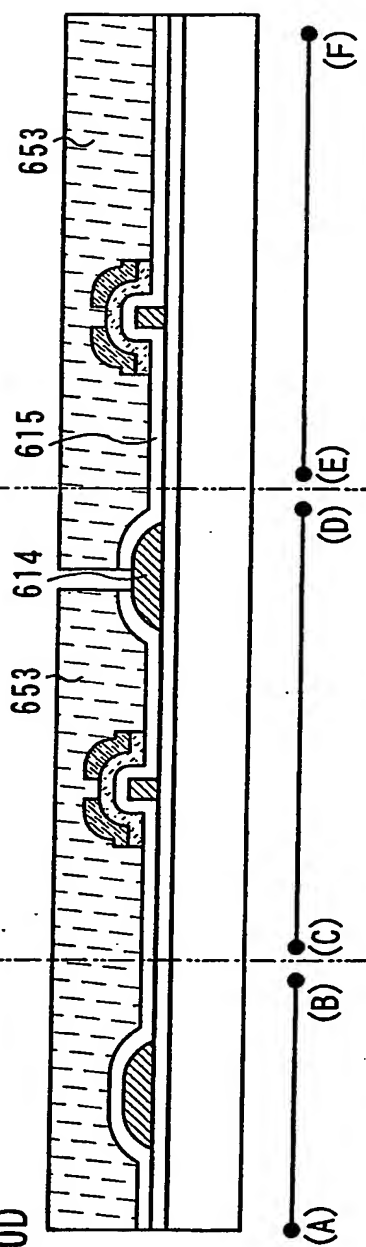


FIG. 31A

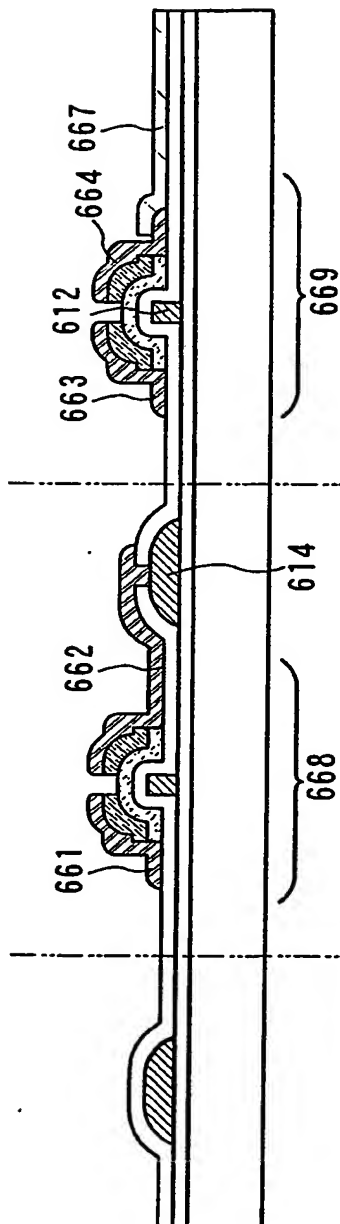
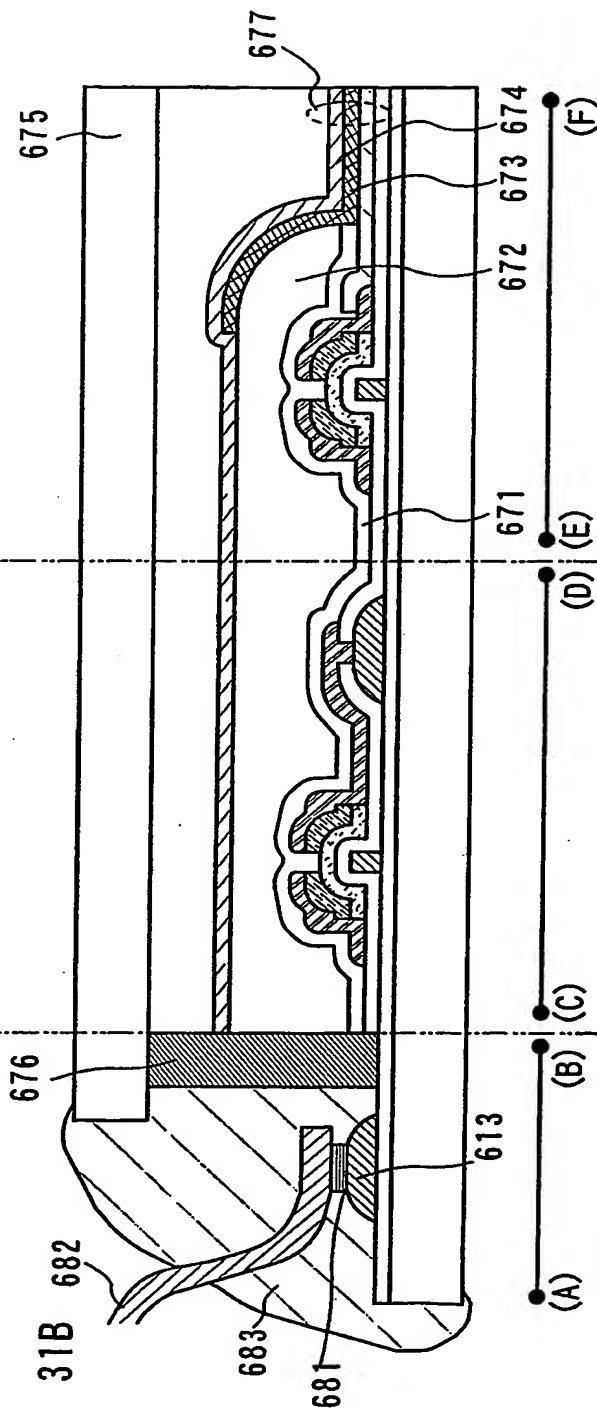


FIG. 31B



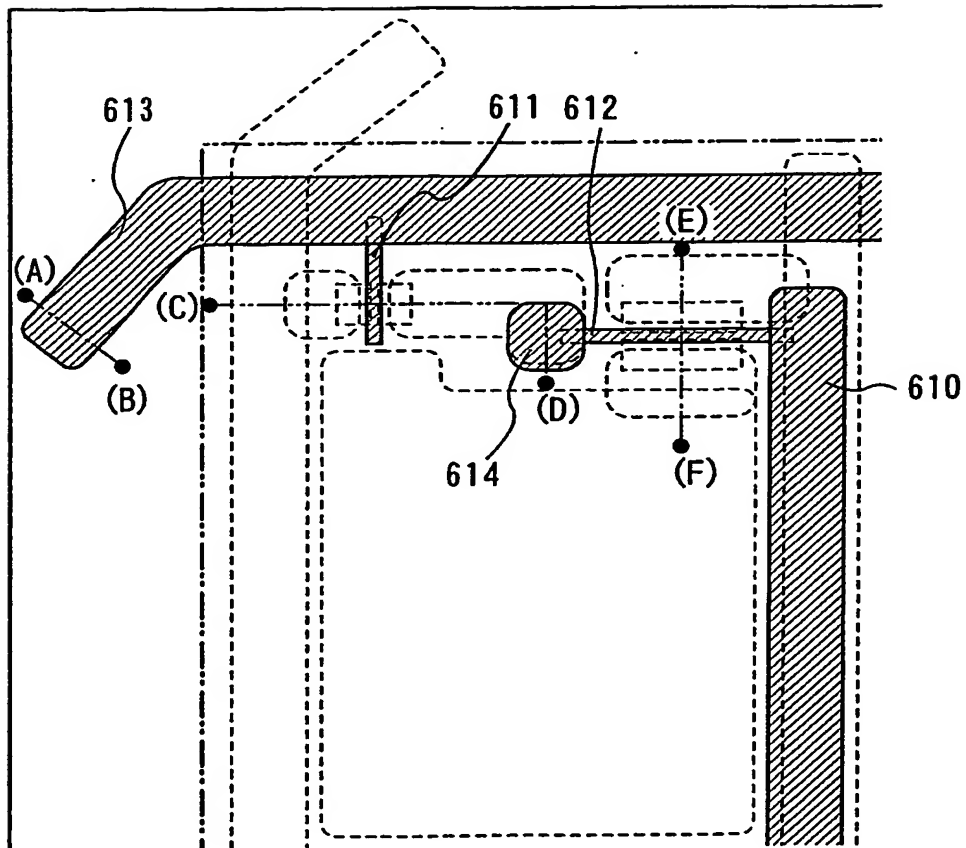


FIG. 32

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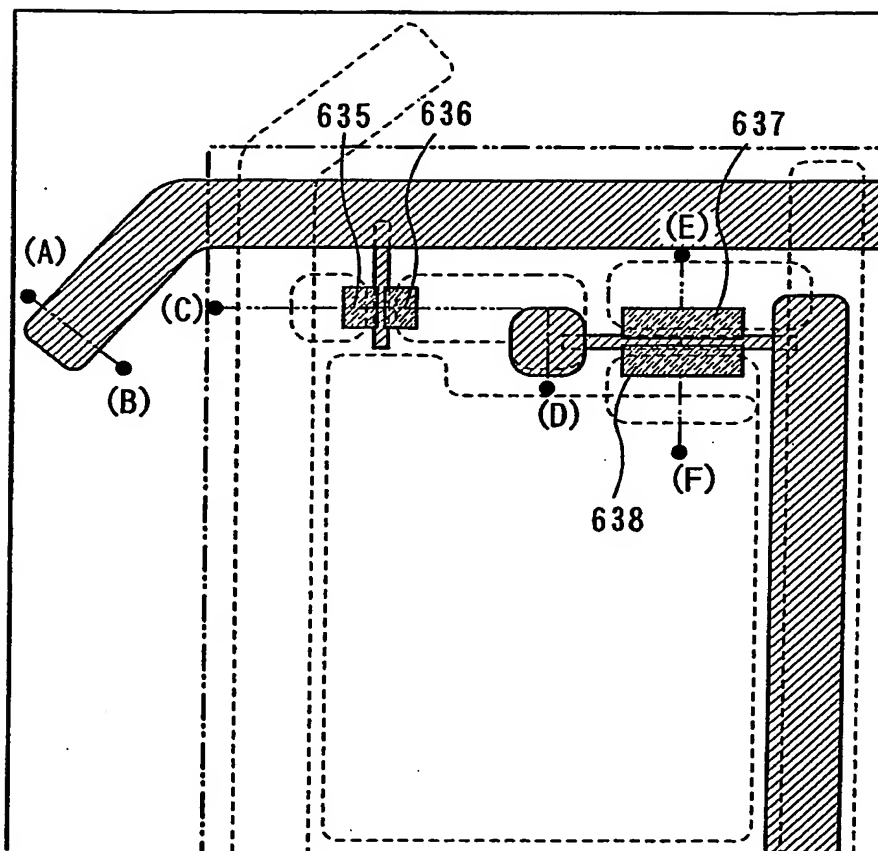


FIG. 33

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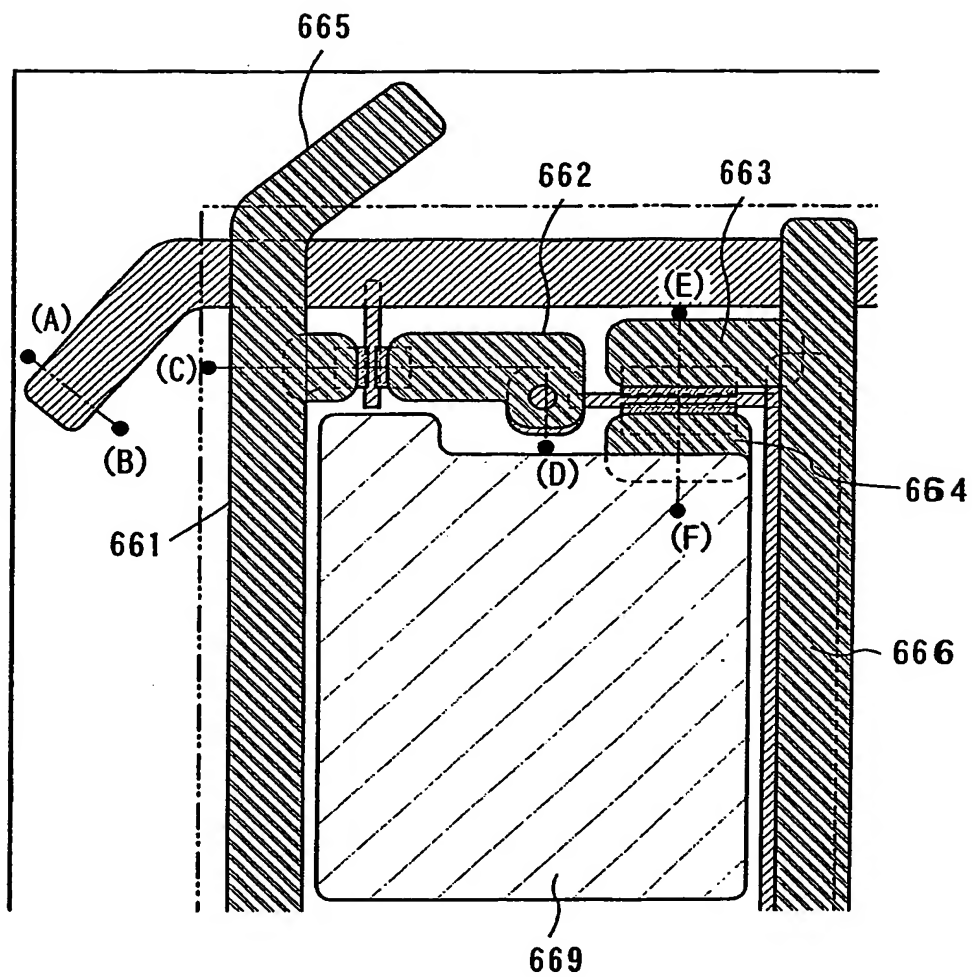


FIG. 34

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FIG. 35A

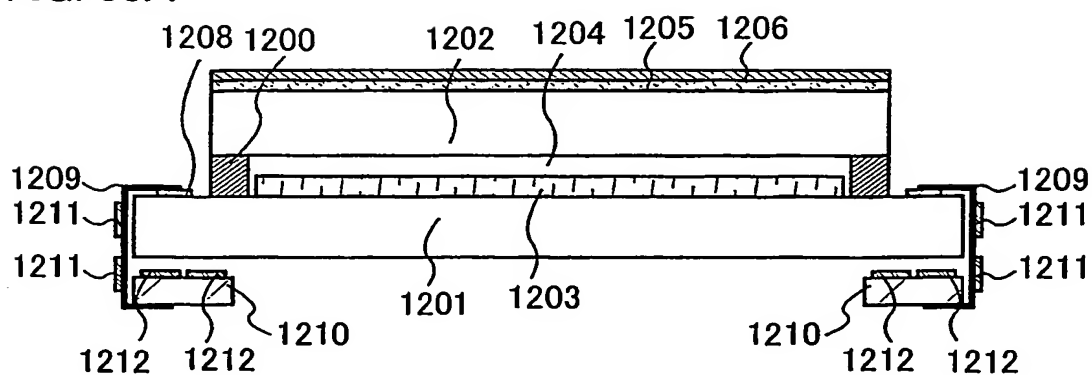


FIG. 35B

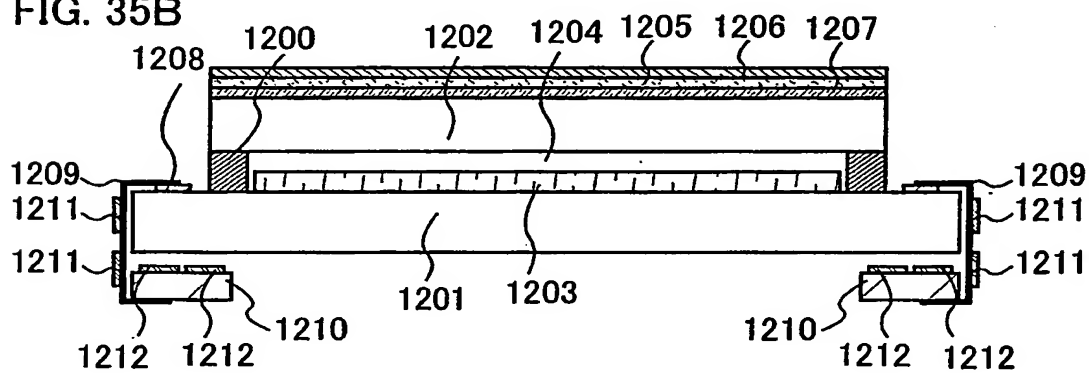
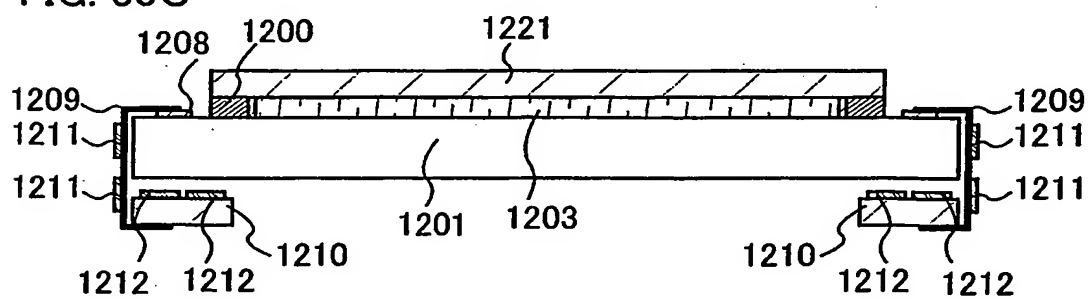


FIG. 35C



EXPLANATION OF REFERENCE

11: Pixel electrode, 16: EL layer, 17: Pixel electrode, 31: Electrode layer, 32: Electrode layer, 33: Electrode layer, 34: Electrode layer, 35: Electrode layer, 41: Hole
5 transport layer, 42: Light emitting layer, 43: Electron injection layer, 100: Substrate,
101: Substrate, 102: Conductive layer, 103: Photosensitive resin, 104: Laser beam, 105:
Mask pattern, 106: Conductive layer, 107: Conductive layer, 110: Pixel, 301: Substrate,
302: Conductive layer, 304: Semiconductor film, 311: Mask pattern, 321: Gate electrode,
322: Insulating film, 323: Semiconductor film, 324: Semiconductor film, 331:
10 Photosensitive resin, 332: Laser beam, 341: Mask pattern, 351: Semiconductor region,
353: Semiconductor region, 354: Drain electrode, 401: Protective film, 411: Mask
pattern, 413: Drain region, 415: Semiconductor region (Channel formation region), 501:
Photosensitive resin, 511: Mask pattern, 513: Drain electrode, 521: Mask pattern, 523:
Semiconductor region, 531: Mask pattern, 532: Semiconductor region, 541: Insulating
15 film, 542: Gate electrode, 543: Photosensitive resin, 544: Laser beam, 551: Mask
pattern, 552: Gate insulating film, 561: Conductive layer, 570: Insulating film, 571:
Mask pattern, 573: Mask pattern, 581: Gate insulating film, 583: Semiconductor film,
584: Photosensitive resin, 585: Mask pattern, 586: Semiconductor region, 587: Gate
insulating film, 588: Conductive layer, 589: Photosensitive resin, 590: laser beam, 591:
20 Mask pattern, 592: Gate electrode, 593: Drain region, 595: Channel formation region,
596: Insulating film (Interlayer insulating film), 597: Conductive film, 600: Substrate,
601: Insulating film, 602: Conductive layer, 604: Photosensitive resin, 606: Laser light,
610: Capacitor electrode layer, 611: Gate electrode layer, 612: Gate electrode layer, 613:
Gate wiring layer, 614: Connection conductive layer, 615: Gate insulating film, 616:
25 Semiconductor film, 617: Semiconductor film, 618: Photosensitive resin, 620: Laser
light, 631: Mask pattern, 632: Channel etch type TFT, 635: Semiconductor region, 641:
Mask pattern, 643: Semiconductor region, 651: Photosensitive resin, 652: Laser light,
661: Source electrode layer, 662: Drain electrode layer, 664: Drain electrode layer, 665:
Source wiring layer, 666: Power supply line layer, 667: Pixel electrode, 668: TFT, 669:
30 TFT, 671: Protective layer, 672: Insulating layer, 673: Light emitting layer, 674: Pixel

electrode, 675: Sealing substrate, 676: Sealant, 677: Light emitting element, 681: Anisotropic conductive layer, 682: Connection terminal, 701: TFT, 702: Capacitor element, 703: TFT, 704: TFT, 705: Light emitting element, 706: TFT, 710: Signal line, 711: Power supply line, 712: Power supply line, 714: Scanning line, 715: Scanning line, 716: Scanning line, 801: Insulating film, 802: Conductive layer, 803: Photosensitive resin, 804: Laser light, 811: Gate wiring layer, 812: Gate wiring layer, 813: Capacitor wiring layer, 814: Gate insulating film, 815: Semiconductor film, 816: Semiconductor film, 817: Photosensitive resin, 818: Laser light, 821: Mask pattern, 823: Semiconductor region, 831: Mask pattern, 832: Semiconductor region, 840: Source wiring layer, 841: Source electrode layer, 842: Drain electrode layer, 843: Pixel electrode, 851: Orientation film, 860: Sealant, 861: Orientation film, 862: Pixel electrode (Opposite electrode), 863: Opposing substrate, 864: Liquid crystal layer, 871: Anisotropic conductive layer, 872: connection terminal, 1001: Laser beam drawing apparatus, 1002: PC, 1003: Laser oscillator, 1004: Power source, 1005: Optical system (ND filter), 1006: Acousto-optic modulator (AOM), 1007: Optical system, 1008: Substrate, 1009: Substrate movement mechanism, 1010: D/A converter, 1011: Driver, 1012: Driver, 1101: Antenna, 1102: Tuner, 1103: Intermediate frequency amplifier (IF amplifier), 1104: Image detection circuit, 1105: Audio detection circuit, 1106: Image processing circuit, 1107: Audio processing circuit, 1108: Image output portion, 1109: Audio output portion, 1151: Chassis, 1152: Display portion, 1153: Speaker portion, 1154: Operational portion, 1155: Video input terminal, 1200: Sealant, 1201: Active matrix substrate, 1202: Sealing substrate, 1203: Pixel portion, 1204: Space, 1205: λ plate, 1206: Polarizing plate, 1207: Colored layer, 1208: Connection terminal, 1209: FPC, 1210: Wiring substrate, 1211: Driver circuit, 1212: External circuit, 1221: Protective film, 1301: Release button, 1302: Main switch, 1303: Viewfinder window, 1304: Flash, 1305: Lens, 1306: Lens barrel, 1307: Chassis, 1311: Viewfinder eyepiece, 1312: Monitor, 1313: Operational button, 1400: Substrate, 1401: Pixel portion, 1402: Signal line driver circuit, 1403: Scanning line driver circuit, 1405: IC chip, 1406: FPC, 1500: Pulse output circuit, 1501: Buffer circuit, 1502: Buffer circuit, 1600: Sealant, 1601: Active matrix substrate, 1602: Opposing substrate, 1603: Pixel portion, 1604: Liquid crystal layer, 1605: Colored layer,

1606: Polarizing plate, 1608: Connection terminal, 1609: FPC, 1610: Wiring substrate,
1611: Driver IC, 1612: External circuit, 1613: Cold cathode fluorescent tube, 1614:
Reflecting plate, 1615: Optical film, 1616: Protective film, 1617: bezel, 1701: Active
matrix substrate, 1702: Electrode pad, 1703: Driver IC, 1704: Connection terminal,
5 1705: Protective insulating film, 1706: Anisotropic conductive adhesive, 1707:
Conductive particle, 1708: Conductive particle, 1711: Buffer layer, 1712: Bump, 1713:
light curable insulating resin, 1721: Adhesive, 1722: Wiring, 1723: Organic resin, 1731:
FPC, 1732: Wiring, 1800: Substrate, 1803: Head, 1804: Imaging means, 1805: Droplet
discharge means, 1807: Control means, 1808: Storage medium, 1809: Image processing
10 means, 1810: Computer, 1811: Marker, 1830: Region, 1831: Stage, 1900: Region, 1901:
Region, 2700: Substrate, 2701: Dispenser, 2702: Sealant, 2703: Pixel portion, 2704:
Liquid crystal material, 2800: Active matrix substrate, 2801: Opposing substrate, 2802:
Sealant, 2803: Pixel region, 2804: Drying agent, 2805: Source wiring, 2806: Gate
wiring, 2807: Pixel, 2811: Semiconductor region, 2812 Pixel electrode, 2814: Drying
15 agent, 3601: TFT, 3602: TFT, 3603: TFT, 3604: TFT, 3605: TFT, 3606: TFT, 3607: TFT,
3608: TFT, 3609: TFT, 3610: TFT, 3611: TFT, 3612: TFT, 3613: TFT, 3620: TFT, 3621:
TFT, 3622: TFT, 3623: TFT, 3624: TFT, 3625: TFT, 3626: TFT, 3627: TFT, 3628: TFT,
3629: TFT, 3630: TFT, 3631: TFT, 3632: TFT, 3633: TFT, 3634: TFT and 3635: TFT.